



4-bit Microcontroller with LCD Driver

FEATURES

- Low power and low voltage operation.
- Powerful instruction set (135 instructions).
- Memory capacity.
 - Instruction ROM capacity 2048 x 16 bits.
 - Index ROM capacity 256 x 8 bits.
 - Internal RAM capacity 128 x 4 bits.
- Input/output ports.
 - Port IOC 4 pins.
 - Buzzer output.
 - INT.
- 8-level subroutine nesting.
- Built-in LCD/LED driver, 4 x 33 = 132 segments.
- Built-in EL driver, frequency or melody generator
- Built-in Resistance-to-Frequency Converter.
- Built-in key strobe function.
- Built-in voltage doubler, halver, tripler charge pump circuit.
- Two 6-bit programmable timers with programmable clock source.
- Watchdog timer.
- 3 external & 5 internal interrupt resources.
- Dual clock operation.
- HALT and STOP function.

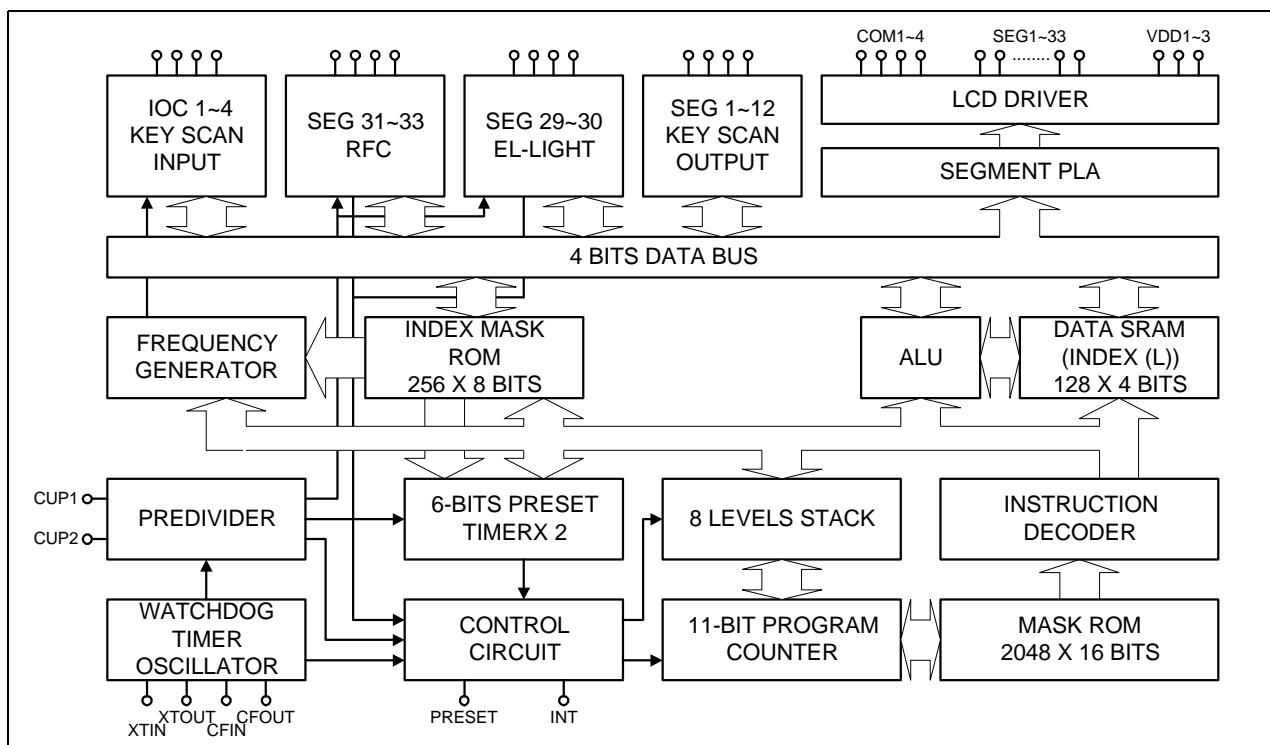
GENERAL DESCRIPTION

The MTU419B is an embedded high-performance 4-bit microcomputer with LCD driver. It contains all the necessary functions in a single chip: 4-bit parallel processing ALU, ROM, RAM, I/O ports, timer, clock generator, dual clock, RFC, alarm, EL-light, LCD driver, look-up table and watchdog timer. The instruction set consists of 135 instructions which include nibble operation, manipulation various conditional branch instructions and LCD data transfer instructions which are powerful and easy to follow.

The halt function stops any internal operations other than the oscillator, divider and LCD driver in order to minimize the power dissipation.

The stop function stops all the clocks in the chip.

BLOCK DIAGRAM



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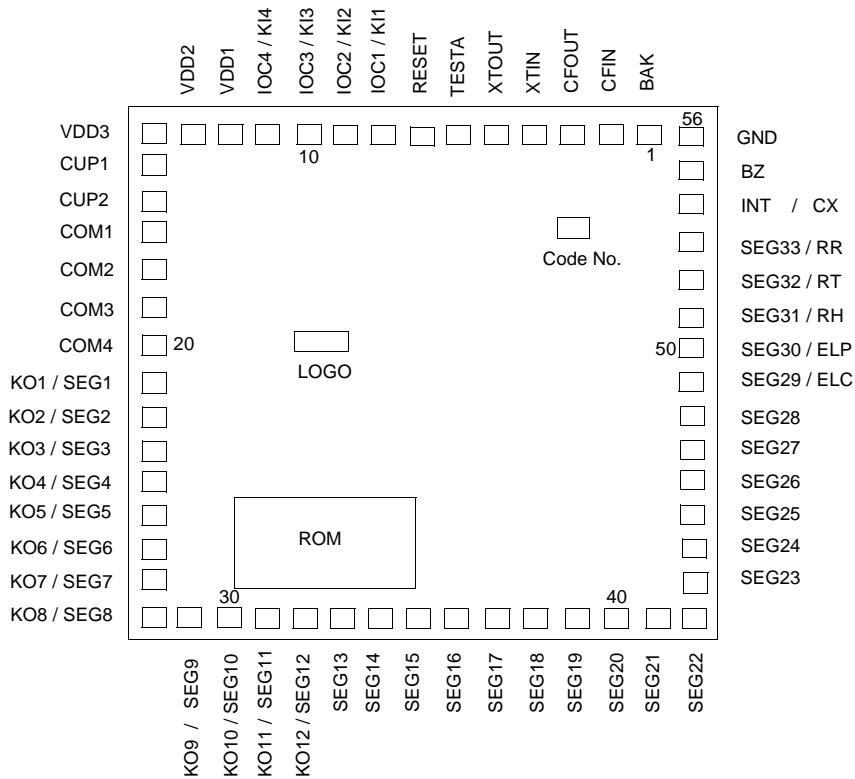
1.0 PAD DIAGRAM

Chip size : 1875 x 1875 μm

Pad size : 100 x 100 μm

Pad window : 90 x 90 μm

Pad pitch : min. 120 μm



Note: The substrate of die must connect to GND.



2.0 PAD ASSIGNMENT

Pad No.	Pad Name	Coordinate		Pad No.	Pad Name	Coordinate	
		X	Y			X	Y
1	BAK	1657.5	1797.5	29	SEG9/KO9	217.5	77.5
2	CFIN	1537.5	1797.5	30	SEG10/KO10	337.5	77.5
3	CFOUT	1417.5	1797.5	31	SEG11/KO11	457.5	77.5
4	XTIN	1297.5	1797.5	32	SEG12/KO12	577.5	77.5
5	XTOUT	1177.5	1797.5	33	SEG13	697.5	77.5
6	TESTA	1057.5	1797.5	34	SEG14	817.5	77.5
7	RESET	937.5	1797.5	35	SEG15	937.5	77.5
8	IOC1/KI1	817.5	1797.5	36	SEG16	1057.5	77.5
9	IOC2/KI2	697.5	1797.5	37	SEG17	1177.5	77.5
10	IOC3/KI3	577.5	1797.5	38	SEG18	1297.5	77.5
11	IOC4/KI4	457.5	1797.5	39	SEG19	1417.5	77.5
12	VDD1	337.5	1797.5	40	SEG20	1537.5	77.5
13	VDD2	217.5	1797.5	41	SEG21	1657.5	77.5
14	VDD3	77.5	1797.5	42	SEG22	1797.5	77.5
15	CUP1	77.5	1657.5	43	SEG23	1797.5	217..5
16	CUP2	77.5	1537.5	44	SEG24	1797.5	337.5
17	COM1	77.5	1417.5	45	SEG25	1797.5	457.5
18	COM2	77.5	1297.5	46	SEG26	1797.5	577.5
19	COM3	77.5	1177.5	47	SEG27	1797.5	697.5
20	COM4	77.5	1057.5	48	SEG28	1797.5	817.5
21	SEG1/KO1	77.5	937.5	49	SEG29/ELC	1797.5	937.5
22	SEG2/KO2	77.5	817.5	50	SEG30/ELP	1797.5	1057.5
23	SEG3/KO3	77.5	697.5	51	SEG31/RH	1797.5	1177.5
24	SEG4/KO4	77.5	577.5	52	SEG32/RT	1797.5	1297.5
25	SEG5/KO5	77.5	457.5	53	SEG33/RR	1797.5	1417.5
26	SEG6/KO6	77.5	337.5	54	INT/CX	1797.5	1537.5
27	SEG7/KO7	77.5	217.5	55	BZ	1797.5	1657.5
28	SEG8/KO8	77.5	77.5	56	GND	1797.5	1797.5



3.0 PAD DESCRIPTIONS

Name	I/O	Descriptions
BAK		Positive back-up voltage. At Li mode, connects a 0.1u capacitance to GND.
VDD1,2,3		LCD drives voltage and positive supply voltage. While Ag mode, connects +1.5V to VDD1. While Li/ExtV mode, connects +3.0V to VDD2.
RESET	I	Input pin from LSI reset request signal. Internal pull-down resistor.
INT	I	Input pin for external INT request signal. Falling or rising edge triggered by mask option. Internal pull-down or pull-up resistor or neither is selected by mask option and shared with CX.
TESTA	I	Test signal input pin.
CUP1,2	O	Switching pins for supplying the LCD driving voltage to the VDD1, 2, 3 pins. Connects the CUP1 and CUP2 pins with nonpolarized electrolytic capacitor if 1/2 or 1/3 bias mode has been selected. In the static mode, these pins should be open.
XIN	I	Time base counter frequency (clock specified, LCD alternating frequency, alarm signal frequency) or system clock oscillation.
XOUT	O	32KHz crystal oscillator. Oscillation stops at the execution of stop instruction.
CFIN	I	System clock oscillation.
CFOUT	O	Connected with ceramic resonator. Connected with RC oscillation circuit. Oscillation stops at the execution of stop or slow instruction.
COM1,2,3,4	O	Output pins for supplying voltage to drive the common pins of the LCD or LED panel.
SEG1-12 / KO1-12	O	Output pins for LCD or LED panel segment. Key strobe function, share pins as key scan output.
SEG13-33	O	Output pins for LCD or LED panel segment.
IOC1-4	I/O	Input / Output port C, can use software to define internal pull-low / low-level hold resistor and chattering clock to reduce input bounce and generate interrupt.
KI1~4	I	Key scan input, this port shares pins with IOC1~4 and is set by mask option.
RFC	CX RR RT RH	1 input pin and 3 output pins for RFC application. This port shares pins with SEG31~33 and INT, and is set by mask option.
EL	ELC ELP	Output port for EL-light. This port shares pins with SEG29,30, and is set by mask option.
ALM	BZ	Output port for alarm, frequency or melody generator.
GND		Negative supply voltage.



4.0 FUNCTIONAL DESCRIPTION

4.1 SRAM

The 128 X 4 bits SRAM is addressing by direct addressing or index addressing mode.

4.2 Index ROM

The 256 X 8 bits index ROM can be used in the 4-bit or 8-bit mode.

4.3 I/O Ports

The IOC port can be selected by software separately as input or output, and with/without internal pull-low and different chattering clocks for halt release / interrupt trigger in order to reduce the input bounce for key scan:

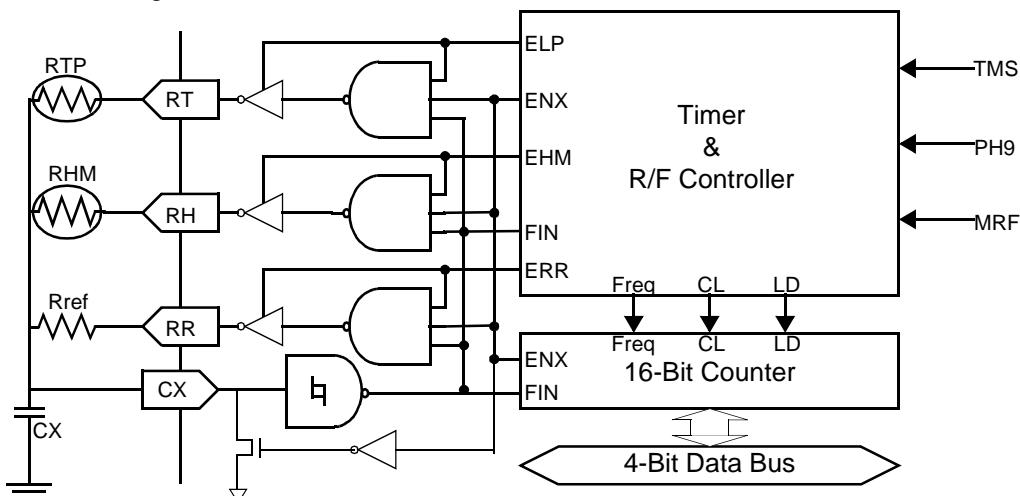
PH6: 512Hz PH8: 128Hz PH10: 32Hz

The initial state of all IOC ports is input mode with pull-low.

Before setting the I/O ports from input to output, execute the output function first to ensure the output state.

4.4 Resistor to Frequency Converter

We use an RC oscillation circuit and a 16-bit counter to calculate the relative resistance of temperature and humidity sensor. The diagram is shown below:

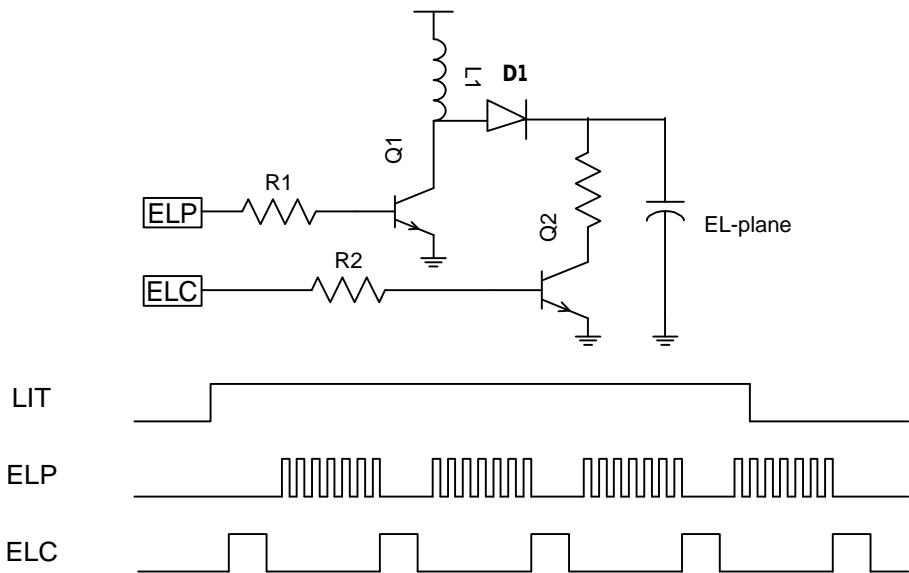


There are two kinds of methodology for measuring the input frequency: first, set FIN (i.e. CX) as the clock input, using timer 2 or the software directly as interval control; second, if the FIN (CX) frequency is too low (either because of a poor resolution for a fixed interval or a longer interval for better resolution but a longer read-out rate [for example, 10 seconds per read-out]), you can switch the measure mode to set FIN (CX) as interval control (it will enable the counter from the first FIN rising edge to the next rising edge, then will generate an interrupt) or use FREQ (internal frequency generator output) as clock input, hence you can count the interval of CX.

To measure the resistor value of temperature and humidity sensor, first we measure the frequency of Rref, then the frequency of Sensor:

$$\begin{aligned} F_{ref} &= K / R_{ref} C_X \text{ and} \\ F_{sensor} &= K / R_{sensor} C_X, \text{ hence} \\ R_{sensor} &= R_{ref} * F_{ref} / F_{sensor}. \end{aligned}$$

Where K is a coefficient for RC-oscillation and will be a constant in a short time period.



4.5 Key_board Scanning Function

SEG1~12 shares the key_board scanning output, the output of the key_board scanning is a P open-drain to VDDO (positive power supply) and all other SEGs and COMs are in Hi-z state during this period. This will minimize the effect of the LCD output.

The segment 1-12 also could be used as keyscan output and LCD still could be displayed with only slightly affected.

SPK 00b5 b4 b3 b2 b1 b0.

b5: 1 will disable key-scan output.

b4: 1 will set all keyscan output as high, if b5=0.

b3~b0: will set the corresponding segment output as 1, if b5=0 and b4=0.

During power on, LCD off, STOP condition. All the common & segment output will be the chips supply power.

4.6 EL-light

Set ELC and ELP clock and duty cycle using ELC X instruction, then turn on and off ELC and ELP output by SF X and RF X instruction. With external transistor, diode, inductor and resistor, we can pump the EL panel to AC 100~250V.

When the EL-light is turned on, the ELC will turn on before ELP, but when the EL-light is off, the ELP and ELC will turn off after the next falling edge of ELC in order to make sure no voltage is left on the EL plane.

4.7 TIMER

The 6-bit programmable timer can select PH3/PH9/PH15/FREQ (Timer 2 can also select PH5/ PH7/ PH11/ PH13 by TM2X instruction) as clock source. When it underflows, the halt release signals are generated.

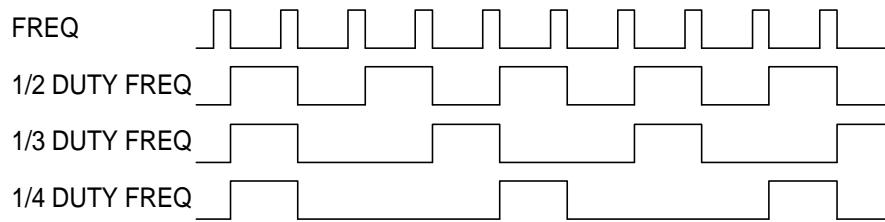
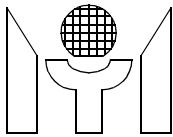
4.8 Predivider

The predivider is a 15-stage counter that uses PH0 as clock source. The output of T-FF is changed when the input signal is changed from H to L. PH11~15 are reset to L when PLC 100H instruction is executed or power on reset or external reset is used. When PH14 is changed from H to L, the halt release signal is generated.

4.9 Alarm / Frequency / Melody

There is an 8-bit programmable counter and an 8-bit envelope control for alarm, frequency or melody output from BZ/BZB.

The frequency counter can use software to select 1/2duty, 1/3duty, 1/4duty drive modes.



4.10 INT Function

The INT pin can be selected by mask option as pull-high/pull-low or none and rising edge/falling edge trigger.

4.11 Watchdog Timer

The watchdog timer automatically generates a device reset when it overflows. The interval of overflow is 8/64/512 x PH10 (set by mask option). You can use software to enable and disable this function. The watchdog enable flag will be disabled by power on reset or reset pin reset condition, but can not be disabled by watch-dog reset itself.

4.12 Halt Function

The halt instruction disables all clocks except predivider, timer, frequency counter, EL-light generator and chattering clock to minimize the operating current.

4.13 Stop Function

The stop instruction disables all clocks to minimize the standby current, so only two external factors (INT, IOC or key scan input) can release the stop condition.



5.0 ABSOLUTE MAXIMUM RATINGS

at Ta = 0 to 70°C , GND = 0V

Name	Symbol	Range	Unit
Maximum Supply Voltage	VDD1	-0.3 to 5.5	V
	VDD2	-0.3 to 5.5	V
	VDD3	-0.3 to 8.5	V
Maximum Input Voltage	Vin	-0.3 to VDD1/2+0.3	V
Maximum Output Voltage	Vout1	-0.3 to VDD1/2+0.3	V
	Vout2	-0.3 to VDD3+0.3	V
Maximum Operating Temperature	Topg	0 to +70	°C
Maximum Storage Temperature	Tstg	-25 to +125	°C

6.0 ALLOWABLE OPERATING CONDITIONS

at Ta = 0 to 70°C , GND = 0V

Name	Symbol	Condition	Min.	Max.	Unit
Supply Voltage	VDD1		1.2	5.25	V
	VDD2		2.4	5.25	V
	VDD3		2.4	8.0	V
Oscillator Start-Up Voltage	VDBB	Crystal Mode	1.3		V
Oscillator Sustain Voltage	VDBB	Crystal Mode	1.2		V
Supply Voltage	VDD1	Ag Mode	1.2	1.65	V
Supply Voltage	VDD2	EXT-V , Li Mode	2.4	5.25	V
Input "H" Voltage	Vih1	Ag Battery Mode	VDD1 - 0.7	VDD1 + 0.7	V
Input "L" Voltage	Vil1	Li Battery Mode	- 0.7	0.7	V
Input "H" Voltage	Vih2		VDD2 - 0.7	VDD2 + 0.7	V
Input "L" Voltage	Vil2		- 0.7	0.7	V
Input "H" Voltage	Vih3	OSCIN at Ag Battery Mode	0.8 x VDD1	VDD1	V
Input "L" Voltage	Vil3		0	0.2 x VDD1	V
Input "H" Voltage	Vih4	OSCIN at Li Battery Mode	0.8 x VDD2	VDD2	V
Input "L" Voltage	Vil4		0	0.2 x VDD2	V
Input "H" Voltage	Vih5	CFIN at Li Battery or EXT-V Mode	0.8 x VDD2	VDD2	V
Input "L" Voltage	Vil5		0	0.2 x VDD2	V
Input "H" Voltage	Vih6	RC Mode	0.8 x VDDO	VDDO	V
Input "L" Voltage	Vil6		0	0.2 x VDDO	V
Operating Freq	Fopg1	Crystal Mode	32	3580	KHz
	Fopg2	External RC Mode	32	1000	KHz
	Fopg3	CF Mode	1000	3580	KHz



Instruction	Machine Code	Functions	Flag/Remark
OR* @HL	0010 1111 1000 0000	AC, @HL $\Leftarrow @HL \text{ OR } AC$	
ADCI Ry,D	0011 0000 DDDD YYYY	AC $\Leftarrow Ry + D + CF$	CF
ADCI* Ry,D	0011 0001 DDDD YYYY	AC, Ry $\Leftarrow Ry + D + CF$	CF
SBCI Ry,D	0011 0010 DDDD YYYY	AC $\Leftarrow Ry + DB + CF$	CF
SBCI* Ry,D	0011 0011 DDDD YYYY	AC, Ry $\Leftarrow Ry + DB + CF$	CF
ADDI Ry,D	0011 0100 DDDD YYYY	AC $\Leftarrow Ry + D$	CF
ADDI* Ry,D	0011 0101 DDDD YYYY	AC, Ry $\Leftarrow Ry + D$	CF
SUBI Ry,D	0011 0110 DDDD YYYY	AC $\Leftarrow Ry + DB + 1$	CF
SUBI* Ry,D	0011 0111 DDDD YYYY	AC, Ry $\Leftarrow Ry + DB + 1$	CF
ADNI Ry,D	0011 1000 DDDD YYYY	AC $\Leftarrow Ry + D$	
ADNI* Ry,D	0011 1001 DDDD YYYY	AC, Ry $\Leftarrow Ry + D$	
ANDI Ry,D	0011 1010 DDDD YYYY	AC $\Leftarrow Ry \text{ AND } D$	
ANDI* Ry,D	0011 1011 DDDD YYYY	AC, Ry $\Leftarrow Ry \text{ AND } D$	
EORI Ry,D	0011 1100 DDDD YYYY	AC $\Leftarrow Ry \text{ EXOR } D$	
EORI* Ry,D	0011 1101 DDDD YYYY	AC, Ry $\Leftarrow Ry \text{ EXOR } D$	
ORI Ry,D	0011 1110 DDDD YYYY	AC $\Leftarrow Ry \text{ OR } D$	
ORI* Ry,D	0011 1111 DDDD YYYY	AC, Ry $\Leftarrow Ry \text{ OR } D$	
INC* Rx	0100 0000 0XXX XXXX	AC, Rx $\Leftarrow Rx + 1$	
INC* @HL	0100 0000 1000 0000	AC, @HL $\Leftarrow @HL + 1$	
DEC Rx	0100 0001 0XXX XXXX	AC, Rx $\Leftarrow Rx - 1$	
DEC* @HL	0100 0001 1000 0000	AC, @HL $\Leftarrow @HL - 1$	
IPC Rx	0100 0111 0XXX XXXX	AC, Rx $\Leftarrow \text{Port}(C)$	
MAF Rx	0100 1010 0XXX XXXX	AC, Rx $\Leftarrow \text{STS1}$	B3 : CF B2 : AC=0 B1 : (No use) B0 : (No use)
MSB Rx	0100 1011 0XXX XXXX	AC, Rx $\Leftarrow \text{STS2}$	B3 : (No use) B2 : SCF2(HRx) B1 : SCF1(CPT) B0 : BCF
MSC Rx	0100 1100 0XXX XXXX	AC, Rx $\Leftarrow \text{STS3}$	B3 : SCF7(PDV) B2 : PH15 B1 : SCF5(TMR1) B0 : SCF4(INT)
MCX Rx	0100 1101 0XXX XXXX	AC, Rx $\Leftarrow \text{STS3X}$	B3 : SCF9(RFC) B2: (no use) B1 : SCF6(TMR2) B0 :(No use)
MSD Rx	0100 1110 0XXX XXXX	AC, Rx $\Leftarrow \text{STS4}$	B3 : (No use) B2 : RFOVF B1 : WDF B0 : CSF
SR0 Rx	0101 0000 0XXX XXXX	ACn, Rxn $\Leftarrow Rx(n+1)$ AC3, Rx3 $\Leftarrow 0$	
SR1 Rx	0101 0001 0XXX XXXX	ACn, Rxn $\Leftarrow Rx(n+1)$ AC3, Rx3 $\Leftarrow 1$	
SL0 Rx	0101 0010 0XXX XXXX	ACn, Rxn $\Leftarrow Rx(n-1)$ AC0, Rx0 $\Leftarrow 0$	



Instruction	Machine Code	Functions		Flag/Remark
SL1 Rx	0101 0011 0XXX XXXX	Can, Rxn AC0, Rx0	\Leftarrow Rx(n-1) \Leftarrow 1	
DAA	0101 0100 0000 0000	AC	\Leftarrow BCD(AC)	
DAA* Rx	0101 0101 0XXX XXXX	AC, Rx	\Leftarrow BCD(AC)	
DAA* @HL	0101 0101 1000 0000	AC, @HL	\Leftarrow BCD(AC)	
DAS	0101 0110 0000 0000	AC	\Leftarrow BCD(AC)	
DAS* Rx	0101 0111 0XXX XXXX	AC, Rx	\Leftarrow BCD(AC)	
DAS* @HL	0101 0111 1000 0000	AC, @HL	\Leftarrow BCD(AC)	
LDS Rx,D	0101 1DDD DXXX XXXX	AC, Rx	\Leftarrow D	
LDH Rx,@HL	0110 0000 0XXX XXXX	AC, Rx	\Leftarrow H(T@HL)	
LDH* Rx,@HL	0110 0001 0XXX XXXX	AC, Rx HL	\Leftarrow H(T@HL) \Leftarrow HL + 1	
LDL Rx,@HL	0110 0010 0XXX XXXX	AC, Rx	\Leftarrow L(T@HL)	
LDL* Rx,@HL	0110 0011 0XXX XXXX	AC, Rx HL	\Leftarrow L(T@HL) \Leftarrow @HL + 1	
MRF1 Rx	0110 0100 0XXX XXXX	AC,Rx	\Leftarrow RFC3-0	
MRF2 Rx	0110 0101 0XXX XXXX	AC,Rx	\Leftarrow RFC7-4	
MRF3 Rx	0110 0110 0XXX XXXX	AC,Rx	\Leftarrow RFC11-8	
MRF4 Rx	0110 0111 0XXX XXXX	AC,Rx	\Leftarrow RFC15-12	
STA Rx	0110 1000 0XXX XXXX	Rx	\Leftarrow AC	
STA @HL	0110 1000 1000 0000	@HL	\Leftarrow AC	
LDA Rx	0110 1100 0XXX XXXX	AC	\Leftarrow Rx	
LDA @HL	0100 1100 1000 0000	AC	\Leftarrow @HL	
MRA Rx	0110 1101 0XXX XXXX	CF	\Leftarrow Rx3	CF
MRW @HL,Rx	0110 1110 0XXX XXXX	AC,@HL	\Leftarrow Rx	
MWR Rx,@HL	0110 1111 0XXX XXXX	AC,Rx	\Leftarrow @HL	
MRW Ry,Rx	0111 0YYY YXXX XXXX	AC,Ry	\Leftarrow Rx	
MWR Rx,Ry	0111 1YYY YXXX XXXX	AC,Rx	\Leftarrow Ry	
JB0 X	1000 0XXX XXXX XXXX	PC	\Leftarrow X	if AC0 = 1
JB1 X	1000 1XXX XXXX XXXX	PC	\Leftarrow X	if AC1 = 1
JB2 X	1001 0XXX XXXX XXXX	PC	\Leftarrow X	if AC2 = 1
JB3 X	1001 1XXX XXXX XXXX	PC	\Leftarrow X	if AC3 = 1
JNZ X	1010 0XXX XXXX XXXX	PC	\Leftarrow X	if AC \neq 0
JNC X	1010 1XXX XXXX XXXX	PC	\Leftarrow X	if CF = 0
JZ X	1011 0XXX XXXX XXXX	PC	\Leftarrow X	if AC = 0
JC X	1011 1XXX XXXX XXXX	PC	\Leftarrow X	if CF = 1
CALL X	1100 0XXX XXXX XXXX	STACK PC	\Leftarrow PC+1 \Leftarrow X	
JMP X	1101 0XXX XXXX XXXX	PC	\Leftarrow X	
RTS	1101 1000 0000 0000	PC	\Leftarrow STACK	CALL Return
SCC X	1101 1001 0X0X 0XXX	X6 = 1 X6 = 0 X4 = 0 X2,1,0=001 X2,1,0=010 X2,1,0=100	: Cfq = BCLK : Cfq = PH0 : Set P(C) : Cch = PH10 : Cch = PH8 : Cch = PH6	
SCA X	1101 1010 000X 0000	X4	: C1-4 Enable (SEF4)	



Instruction	Machine Code	Functions	Flag/Remark
SPC X	1101 1110 000X XXXX	X4 : Set C4-1 Pull-Low / Low-Level-Hold X3~0 : Set C4-1 I/O	
SPK Rx	1100 0011 00XX XXXX	X5=1 : Set all Hi-z X4=1 : Set all 1 X3~0 : Set n of 12	
SPKI X	0000 101X 0000 0000	X8=0 : Set HRF5 from port C / key scan input X8=1 : Set HRF5 from key strobe signal	
IPI Rx	0100 0010 1XXX XXXX	[Rx] AC ⇐ 11160 HRF5 control bit	
TMS Rx	1110 0000 0XXX XXXX	Timer1 ⇐ Rx, AC	
TMS @HL	1110 0001 0000 0000	Timer1 ⇐ T@HL	
TMSX X	1110 0010 XXXX XXXX	X7,6 = 11 : Ctm = FREQ X7,6 = 10 : Ctm = PH15 X7,6 = 01 : Ctm = PH3 X7,6 = 00 : Ctm = PH9 X5~0 : Set Timer1 Value	
TM2 Rx	1110 0100 0XXX XXXX	Timer2 ⇐ Rx, AC	
TM2 @HL	1110 0101 0000 0000	Timer2 ⇐ T@HL	
TM2X X	1110 011X XXXX XXXX	X8,7,6=111 : Ctm = PH13 X8,7,6=110 : Ctm = PH11 X8,7,6=101 : Ctm = PH7 X8,7,6=000 : Ctm = PH5 X8,7,6=011 : Ctm = FREQ X8,7,6=010 : Ctm = PH15 X8,7,6=001 : Ctm = PH3 X8,7,6=000 : Ctm = PH9 X5~0 : Set Timer2 Value	
SHE X	1110 1000 0XXX XXX0	X6 : Enable HEF6(RFC) X5 : Enable HEF5(KEY) X4 : Enable HEF4(TMR2) X3 : Enable HEF3(PDV) X2 : Enable HEF2(INT) X1 : Enable HEF1(TMR1)	
SIE* X	1110 1001 0XXX XXXX	X6 : Enable IEF6(RFC) X5 : Enable IEF5(KEY) X4 : Enable IEF4(TMR2) X3 : Enable IEF3(PDV) X2 : Enable IEF2(INT) X1 : Enable IEF1(TMR1) X0 : Enable IEF0(A,CPT)	
PLC X	1110 101X 0XXX XXXX	X8 : Reset PH15~11 X6~0 : Reset HRF6~0	
SRF X	1110 1100 00XX XXXX	X5 : Enable Cx Control X4 : Enable Timer2 Control X3 : Enable Counter X2 : Enable RH Output X1 : Enable RT Output X0 : Enable RR Output	ENX EHM ETP ERR



Instruction	Machine Code	Functions		Flag/Remark
SRE X	1110 1101 X0XX 0000	X6~4	: Enable SRF7,5-4	SRF7 (KEY) SRF5 (HRF2) SRF4 (M Port)
FAST	1110 1110 0000 0000	SCLK	: High Speed Clock	
SLOW	1110 1111 0000 0000	SCLK	: Low Speed Clock	
SF X	1111 0000 X00X XXXX	X7 X4 X3 X2 X1 X0	: Reload Set : WDT Enable : HALT after EL LIGHT : EL LIGHT On : BCF Set : CF Set	RL1 WDF BCF CF
RF X	1111 0100 X00X 0XXX	X7 X4 X2 X1 X0	: Reload Reset : WDT Reset : EL LIGHT Off : BCF Reset : CF Reset	RL1 WDF BCF CF
SF2 X	1111 1000 0000 0XXX	X0 X1 X2	: Reload Set : Dis-ENX Set : Close all segments	RL2 DED RSOFF
RF2 X	1111 1001 0000 0XXX	X0 X1 X2	: Reload Reset : Dis-ENX Reset : Release all Segments	RL2 DED RSOFF
ALM X	1111 101X XXXX XXXX	X8,7,6=111 X8,7,6=100 X8,7,6=011 X8,7,6=010 X8,7,6=001 X8,7,6=000 X5~0	: FREQ : DC1 : PH3 : PH4 : PH5 : DC0 ≤ PH15~10	
ELC X	1111 110X XXXX XXXX	X8=1 X8=0 X7,6=11 X7,6=10 X7,6=01 X7,6=00 X5,4=11 X5,4=10 X5,4=01 X5,4=00 X3,2=11 X3,2=10 X3,2=01 X3,2=00 X1,0=11 X1,0=10 X1,0=01 X1,0=00	BCLKX PH0 BCLK/8 BCLK/4 BCLK/2 BCLK 1/1 1/2 1/3 1/4 PH5 PH6 PH7 PH8 1/1 1/2 1/3 1/4	ELP - CLK BCLKX ELP - DUTY ELC - CLK ELC - DUTY
HALT	1111 1110 0000 0000	Halt Operation		
STOP	1111 1111 0000 0000	Stop Operation		



8.1 Symbol Description

AC	: Accumulator	D	: Immediate data
ACn	: Accumulator bit-n	PC	: Program counter
X	: Address	CF	: Carry flag
Rx	: Memory of address X	Rxn	: Memory bit-n of address X
WDF	: Watchdog timer enable flag	Ry	: Memory of working register Y
HL	: Index register	BCF	: Back-up flag
BCLK	: System clock address	@HL	: Memory of index RAM
IEFn	: Interrupt enable flag	HRFn	: Halt release flag
SRFn	: Stop release enable flag	HEFn	: Halt release enable flag
SCFn	: Start condition flag	Cfq	: Clock source of frequency generator
Cch	: Clock source of chartering detector	Ctm	: Clock source of timer
TMR	: Timer overflow release flag	PDV	: Predivider
SEFn	: Switch enable flag	Lz	: LCD latch
FREQ	: Frequency generator setting value	T@HL	: Memory of index ROM
ADF	: ADC flag	CSF	: Clock source flag
DAC	: Digital-to-analog converter output signal	L	: Low address of index
LBR	: Low-battery voltage reference	RFOVF	: RFC overflow flag
H	: High address of index	LT@HL	: Low nibble of index ROM
HT@HL	: High nibble of index ROM		



9.0 APPENDIX (Important Issue for MTU419/419B/428/429B)

9.1 Chip's internal vlotage V.S. power mode and external connection

	AG	LI	EXT-V
VDD1	Vsupply	1/2 x Vsupply	1/2 x Vsupply
VDD2	2 x VDD1	Vsupply	Vsupply
VDD3 *1	3 x VDD1	3/2 x Vsupply	3/2 x Vsupply
VDD4 *2	4 x VDD1	2 x Vsupply	2 x Vsupply
BAK *3	VDD1	BCF = 0 VDD1	BCF=1 VDD2

Note *1: VDD3 is only used for LCD operating in 1/3 bias and 1/4 bias. If 1/2 bias chosen, VDD3 need be connected to VDD2 (VDD3 is equal to VDD2).

*2: VDD4 is only used for LCD operating in 1/4 bias. If 1/3 bias chosen, VDD4 need be connected to VDD3 (VDD4 is equal to VDD3). If 1/2 bias chosen, VDD4 need be connected to VDD2 (VDD4 is equal to VDD2).

*3: BAK is defined as chip's internal power supply node, which is used only for internal logic circuitry.

- A. Whatever the power mode used, all external VDD# pins must connect a capacitor (0.05uF or 0.1uF) to GND for decoupling power noise using.
- B. All VDD# pins other than Vsupply are from voltage charge pump, i.e. If no clock, then VDD# pins can not supply out.
- C. Vsupply is the power supply for Chip and depends on the power mode used, all the input and output pins voltage range follow the Vsupply.

9.2 The capacitor connected between CUP2 and CUP3 is only when MTU429B operating in 1/4 bias.

9.3 Some notes for BCF flag

BCF is always set to 'High" automatically after Power on, Reset and Stop mode.

- A. For power saving use, BCF may be set to 'Low" which can reduce chip's current consumption.
- B. Ag and Li battery mode applications:
After Power on, Reset or release from Stop mode. Need to wait 2 seconds long, then can set BCF to 'Low".
- C. Larger current load and fast clock:
 - a. BCF should be set to 'High" for the case of fast clock or larger current load (such as RFC, ADC, DAC, EL-light and Buzzer output) use.
 - b. After set BCF to 'high", need wait 2 ms long at least, then can enable larger current load. Or after disable Larger current load, need wait 2ms long at least, then can set BCF to 'Low"
- D. Li battery mode applications:
Especially for Li battery mode, BCF switching will cause a temporary current surge (or power noise) on BAK. Furthermore if not necessary, dont switch BCF too often as possible.
- E. Improperly use of BCF will cause malfunction to chips.



F. Lower current consumption and reliability:

The chip's reliability will greatly decrease if invalid use BCF, especially for Li-battery mode. Because the chip's internal power also switches between VDD1 and VDD2, which also cause a temporary power noise.

9.4 Input pin

Any input pins floating will cause chips in malfunction and large current consumption.

9.5 32.768KHz Xtal oscillator

Always layout the Xtal as close to the Chips as possible and don't place any signals across the layout routing. Since Xtal oscillation circuit consumes current only 0.5uA to 1uA, any power noise will disturb the oscillation. The proper external capacitors for Xin and Xout are necessary for the accuracy and stability of oscillation.

$$1/(C_{in}+C_{pcb}) + 1/(C_{out}+C_{pcb}) = 1/CL$$

The Chip's Xout pin has an internal capacitor around 10~20pf connected to BAK (chip's internal Node).

For example

Epson's C-001R 20ppm, CL=12.5pf

Cin = 25pf

Cout = 15pf

The time accuracy will be around +/- 0.5 second/day

Note: The parasitic capacitors of Xtal pins in PCB layout need be considered in above calculation.

9.6 RFC / Event counter / IOA for MTU429B

If anyone uses RFC / Event counter function and IOAs in the same application, make sure the pin IOA1 (which is corresponding to CX by mask option) must set as IOA's output mode by SPA instruction. Or the signal changes on CX pin may cause halt release or interrupt for IOA's port. In this case the program couldn't function properly.